

PRODUCT CHANGE NOTICE PCN Form (D4-E000-73)

PCN#10-023

NOTIFICATION DATE: January 12, 2011

MODEL(S) AFFECTED:

Case Style XX211-1 for MSW-2-20, MSW-2-20+, MSWA-2-20, MSWA-2-20+

EXTENT OF CHANGE:

Change of plating

MSW-2-20 & MSWA-2-20: Discontinuation of SnPb plating

MSW-2-20+ & MSWA-2-20+: Change from Tin plate to Matte Tin/Silver/Nickel plating

Die Change

EFFECT OF CHANGE:

- No change in fit, form or function.
- Discontinuation of non-RoHS finish as stock is depleted.
- Change of existing RoHS finish to qualified plating used in other Mini-Circuits MMIC devices
- Minor change in performance resulting from new die (see datasheets)

REASON FOR CHANGE:

- Changes made to enable improvements in manufacturing throughput in compliance with Industry requirements for RoHS
- Transition of wafer fab.

EFFECTIVE DATE OF CHANGE:

Immediate

DELIVERY:

Delivery of both versions of RoHS finish will be made concurrently

ATTACHMENTS:

N/A

QUESTIONS?

PLEASE CONTACT US.

ISO 9001 ISO 14001 AS 9100 CERTIFIED

Refer to Procedure: D3-E040